

Assembly of the first 1 m^2 Micromegas with digital readout for a sDHCAL

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Outline

Micromegas DHCAL project

Concept, performance, m^2 design

$48 \times 32 \text{ cm}^2$ Active Sensor Units

Description and characterisation

1 m^2 prototype

Assembly

Conclusion and future plans

Micromegas DHCAL project

- Calorimetry based on PFA at future linear colliders:
granularity more important than resolution
→ digital readout of 1 cm² cells

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→ digital readout of 1 cm² cells
- Loss of linearity at high energy (≥ 100 GeV/c)
→ semi-digital readout
- Large area with gaseous detectors
→ RPC, GEM, Micromegas

Micromegas DHCAL project

Pros

Proportionality

Low working voltage (≤ 500 V)

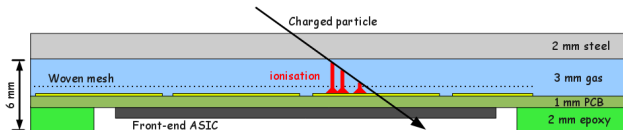
Standard mix (Ar, iC₄H₁₀, CO₂)

Industrial production (Bulk)

Cons

Sparks (rate, gain dependent)

Small charges (≈ 25 fC for MIPs)



R&D efforts for the construction of a
 physics and technological sDHCAL prototype of 1 m³
 → 40 planes of 1 m² each (20 mm SS + 8 mm detector)

Performance with small prototypes

- Tests with MIPs carried out at SPS/H2 in 2008
 - 97 % efficiency at 1.5 fC threshold
 - multiplicity below 1.12 (1.5 fC)
 - uniformity better than 1 % over 100 cm²

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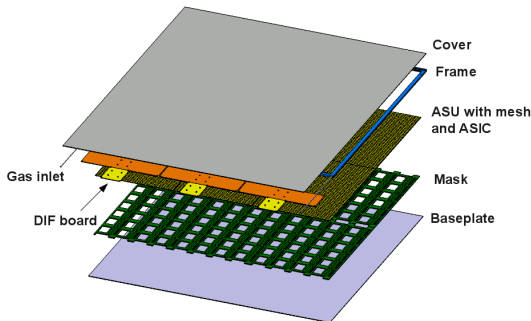
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 - 2.36 % K/mbar
- Most results available in 2009 **JINST** 4 P11023

Design of the 1 m² prototype

- 6 Active Sensor Units (ASU) of 32×48 cm²
- 24 ASIC with 64 channels (per ASU)
- 12 mm thick including 4 mm stainless steel (covers)
- Active area of 9216/10⁴ ≈ 93 %
- Assembly procedure validated with mechanical prototype



ASU with HARDROC2

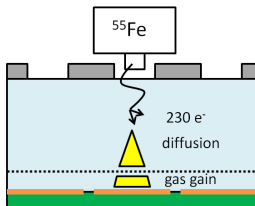
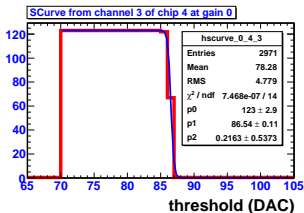
- HARDROC2 (64 channels) circuitry:
 - current preamplifier with adjustable gain (0–2)
 - slow/fast shaper for analog/digital readout
 - 3 discriminators with adjustable threshold (individual gains but 3 common threshold)
 - 200 ns timestamping of hits
 - 128 event depth memory
 - power pulsing capability (not used so far)

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 - power pulsing capability (not used so far)
- Fast shaper time constant (20 ns) too short w.r.t. Micromegas signals (150 ns)
 - poor efficiency
 - work on new chip with LAL/Omega on-going (MICROROC)

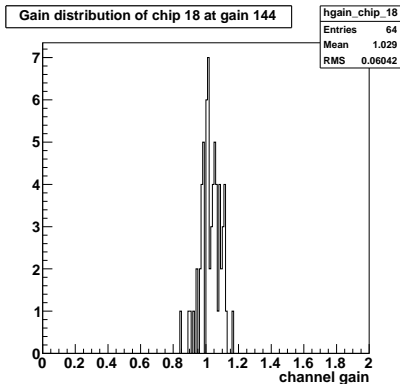
ASU characterisation

- Electronic test
 - measure noise level
 - identify noisy channels
 - measure preamp gain
 - achieve lowest threshold
- Test in a gas chamber
 - ⁵⁵Fe quanta
 - study chip parameters
 - effect of drift and amplification field



Preamplifier gain measurements

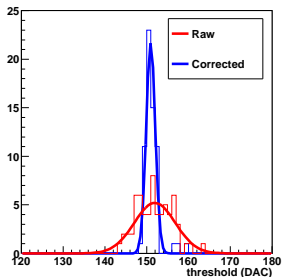
- Measure Scurves for different input charges (0,20,100,200 fC)
Agilent pulse generator and attenuator
- Calculate slope of inflexion point VS input charge variations



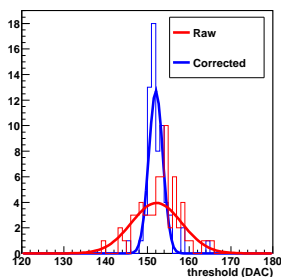
Gain equalization

- Apply correction factor to preamplifier gain g
 - simply calculated as \bar{g}/g_i
 - check equalization with charge injection:
Chip 18: 3.2 % → 0.8 % Chip 24: 4.0 % → 1.2 %

100 fC inflexion point - chip 18 - asu 12



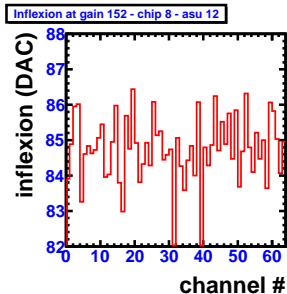
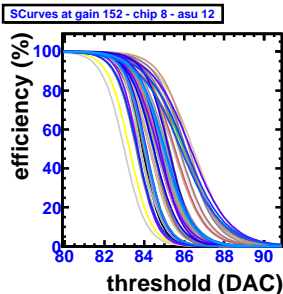
100 fC inflexion point - chip 24 - asu 12



- Uniform response of HCAL will be important
however, most important with HR2 is to achieve low threshold

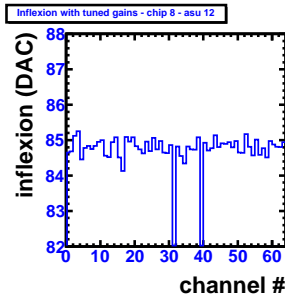
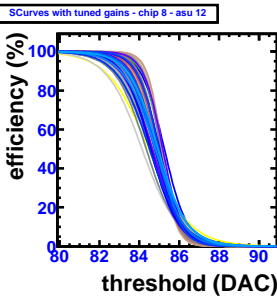
Pedestal alignment

- How to reach the minimum charge threshold?
 - Ideal case: all pedestal Scurves super-imposed
→ threshold 5σ above the inflexion point μ
 - Unfortunately: at same preamp gain, dispersion of μ_i and σ_i
 - But: μ_i and σ_i depends linearly on preamp gain
→ adjust gains g_i to minimize spread of μ_i or $(\mu_i + 5\sigma_i)$



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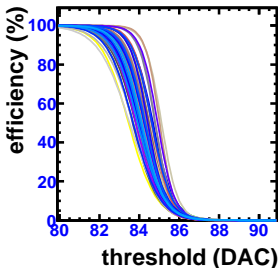
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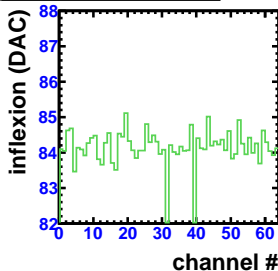
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SCurves with tuned gains - chip 8 - asu 12

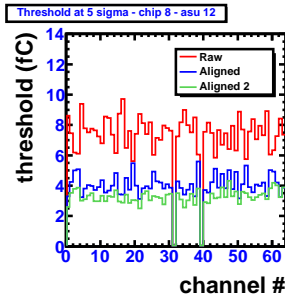
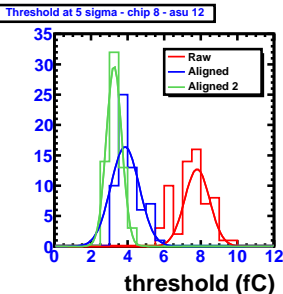


Inflexion with tuned gains - chip 8 - asu 12



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- Gas test box
 - Volume of 8 L (3 cm drift gap), perforated cover for testing individual channels
 - 2 guard electrodes, ⁵⁵Fe X-rays transparent cathode

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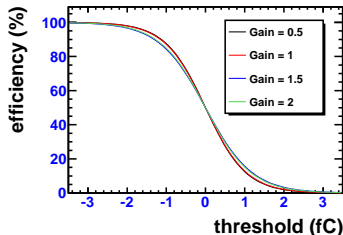
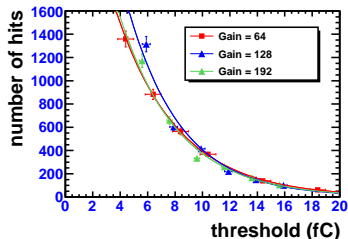
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 - 2 guard electrodes, ⁵⁵Fe X-rays transparent cathode
- ⁵⁵Fe quanta yields on average 230 electrons
 - Longitudinal diffusion gives $\sigma_t = D_L \sqrt{z} / v_d = 13 \sqrt{z}$ ns
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- Method:
 - External signal triggers the readout of the detector (30 Hz)
 - Count the number of hits recorded on the tested pad

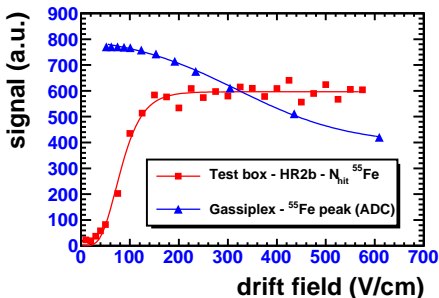
Preamplifier gain

- For a different preamp gains (0.5,1,1.5)
 - Decrease threshold from high value to noise level
 - Signal to noise ratio similar
→ same number of hits



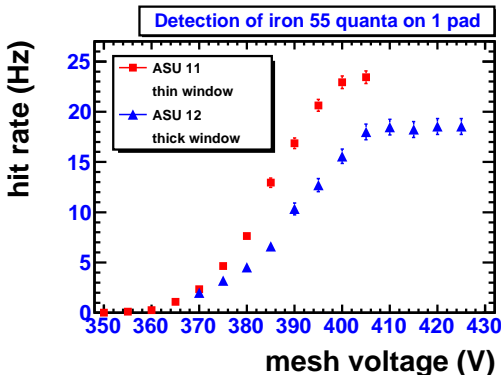
Drift field

- Combination of three effects:
 - Collection efficiency drops above certain field
 - Drift velocity has a local maximum, 4.2 cm/ μ s at 250 V/cm
 - Long. diffusion coefficient drops:
450–200 μ m/ $\sqrt{\text{cm}}$ at 100–1000 V/cm
- Last two effects govern time spread of the e⁻ at the mesh



Amplification field

- At higher amplification field:
 - Total charge induced on pad increases ($\sim \exp(\alpha d)$)
 - But fraction $Q_{\text{electrons}}/Q_{\text{ions}}$ drops ($\sim 1/\alpha d$)
- Net effect is an increase of the number of detected photons
- Plateau reached at 410 V at which the gas gain is about 10^4



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 - 1 equipped with HR2b (bug in the chip fixed)

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- Prior at assembly:
 - ASU "trained" under high voltage (800 V in air)
 - electronic test (pedestals, calibration ...)

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 - electronic test (pedestals, calibration ...)
- Assembly started Monday last week, ready for test on Saturday

ASU glueing

- HV and electronics tests
- Glueing of ASU slab on a vetronite mask



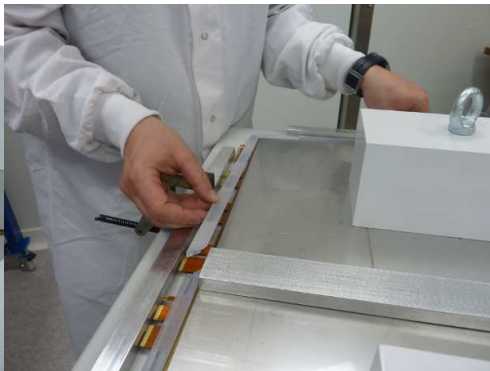
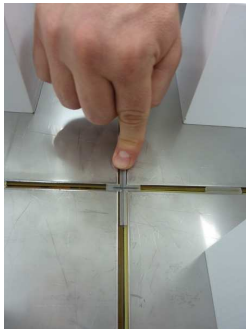
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Spacers and frame glueing

- Spacers will define the 3 mm gas gap
- Frame insure gas distribution and tightness



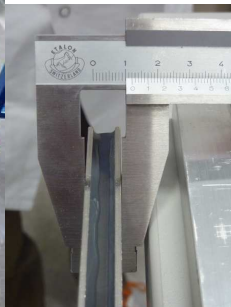
Cathode and cover glueing

- Cathode is a copper foil glued on stainless steel plate
- Cover area larger than 1 m² to support the readout electronics



After assembly

- Connection failure of one flexible cable
→ 1 row of chip over 12 is not responding, rest is fine
- Total thickness is 12 mm which includes 4 mm of steel
→ effective thickness of 8 mm complies with ILC goal
could be reduced to 6 mm



Conclusion and future plans

- About to complete an important milestone of the project: fabrication and characterisation of the first 1 m² Micromegas prototype with embedded digital electronics
- Focus in the 2 coming weeks on beam test at SPS/H4 starting on June 10th
Comics test at LAPP till then
- Due to short shaping of HR2, poor efficiency expected
→ work on a new chip is on-going in collaboration with LAL/Omega
- New chips available before the end of the year
→ more 1 m² prototype not before next year